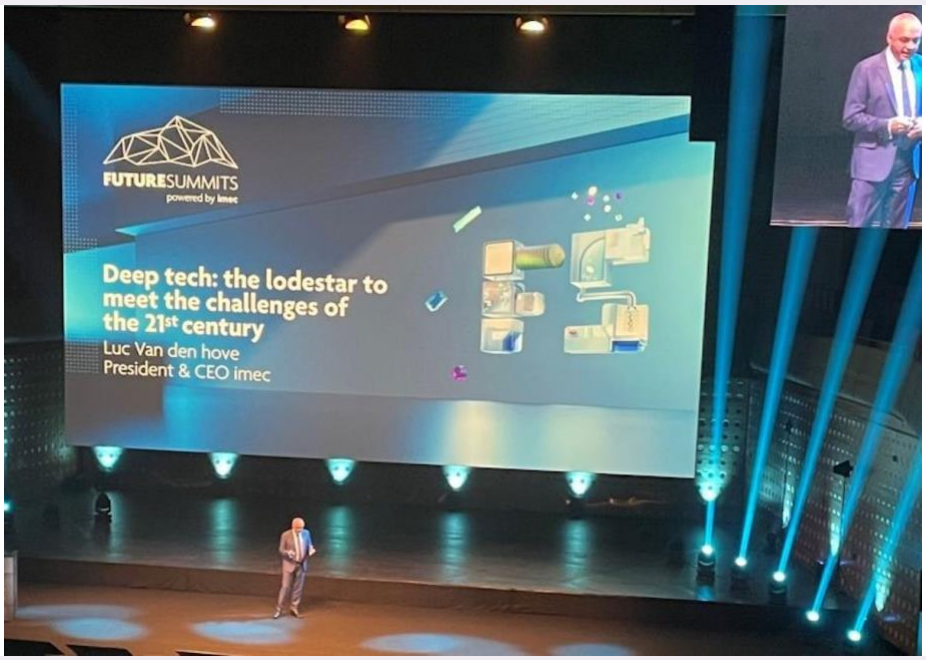
EV Group Earns Outstanding 10th Consecutive Triple Crown Win in TechInsights 2022 Customer Satisfaction Survey - June 17, 2022



Semiconductor Industry R&D is Alive and Well

The decline of centralized semiconductor industry R&D labs, as well as the technical challenges facing semiconductor manufacturers, have helped the rise of independent research and development institutions. These organizations such as imec and CEA-LETI, both in Europe, are funded in part by local and regional governments, but more importantly, they are funded by companies either performing pre-competitive research with the R&D centers as the primary project manager, or companies that choose to use imec or Leti as an extension of their research centers and use the R&D centers resources in addition to those of their own.

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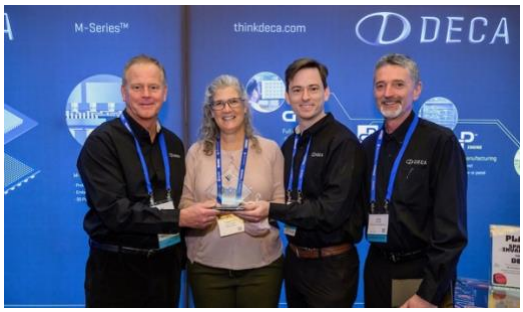

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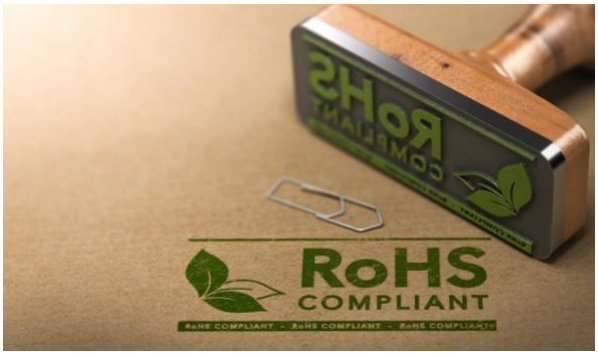

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ADVANCED SYSTEM IN PACKAGE TECHNOLOGY
CONFERENCE & EXHIBITION
June 21-23, 2022
DoubleTree by Hilton Sonoma - Wine Country

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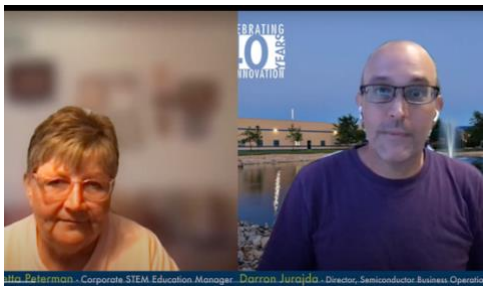

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[Onto Announces New EB40 All-Surface Inspection Module for Wafer Fabs and Advanced Packaging]

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Events

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[SEMICON West HYBRID 2022]
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[IEEE IEDM 2022 Call for Papers July 14 Deadline]

[9th ESTC (Electronics System-Integration Technology Conference)]
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